

are arranged in groups along the sides of the semiconductor die, i.e. there are five leads along each of the longer sides of the rectangular die and three leads along each of the shorter sides. Those leads are arranged in distinct groups, and all of the leads are not evenly distributed around the semiconductor die mount as required by Claims 1 and 5 and around the four sides and corners of the die as required by Claim 2. The same is true of Ootsuki's Figures 5, 9B, 10B, 11B, 12B, and 16B. Therefore, Applicant respectfully submits that Claims 1 and 5, as well as Claims 2-4 and 6 depending therefrom, are patentable in view of Ootsuki.

In view of the above, Applicant respectfully requests the entry of this amendment, the withdrawal of the Examiner's rejections, and allowance of claims 1-6. If the Examiner has any questions or other correspondence regarding this application, Applicant requests that the Examiner contact Applicant's attorney at the below listed telephone number and address.

Respectfully submitted,



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## Version with Markings to Show Changes Made

### Claims

1. (twice amended) A strapless lead frame/heat slug combination, comprising:  
[a plurality of] lead frame leads, all of said leads being evenly distributed around a semiconductor die mount area; and  
a heat slug providing the die mount area, wherein said heat slug is attached under the lead frame with tape.
2. (twice amended) The strapless lead frame according to Claim 1, wherein the semiconductor die has four sides and corners, and the lead frame leads are all evenly distributed on each of the four sides and around the corners.
5. (twice amended) A strapless lead frame for use with heat slug packages, comprising:  
[a plurality of] lead frame leads, all of said leads being evenly distributed around a semiconductor die mount area; and  
a heat slug providing a rectangular die mount area, wherein said heat slug is attached under the lead frame with tape, there being the same number of lead frame leads on opposite sides of the lead frame and a different number of lead frame leads on adjacent sides of the lead frame.